

## **FB250M thru 260M**

## SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

# REVERSE VOLTAGE – 50 to 60Volts FORWARD CURRENT – 2.0 Ampere

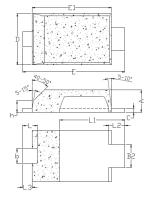
#### **FEATURES**

- Very low profile package 0.80mm
- · High efficiency
- · Extremely fast switching
- Negligible switching losses
- · Low forward voltage drop, low power loss

#### **MECHANICAL DATA**

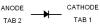
- Case: JEDEC DO-222AA
- Case Material: "Green" molding compound, UL flammability classification 94V-0, (No Br. Sb. Cl.)
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Lead Free Plating (Matte Tin Finish.)
- Reliability tested in accordance with AEC-Q101
- Component in accordance to RoHs 2002/95/EC

### **Mite Flat**



DO-222AA					
DIM.	MIN.	MAX.			
Α	0.80	0.95			
b	0.40	0.65			
b2	0.70	1.00			
С	0.10	0.25			
D	1.75	2.05			
E	3.60	3.90			
E1	2.80	3.10			
h	0.35	0.50			
L	0.50	0.80			
L1	2.10	2.60			
L2	0.45	0.75			
L3	0.20	0.50			
All Dimension in millimeter					

REV. 2, Oct-2010, KSHP06



#### **MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

PARAMETER		SYMBOL	FB250M	FB260M	UNIT	
Device marking code		Note	B25	B26		
Maximum Repetitive Peak Reverse Voltage		V <sub>RRM</sub>	50	60	V	
Maximum RMS Voltage		V <sub>RMS</sub>	35	42	V	
Maximum DC Blocking Voltage		$V_{DC}$	50	60	V	
Average Rectified Output Current @T <sub>L</sub> =75°C		I <sub>(AV)</sub>	2.	2.0		
Peak Forward Surge Current 8.3ms single half sine-wave		I <sub>FSM</sub>	5	50		
Operating junction temperature range		TJ	-55 to	-55 to +125		
Storage temperature range		T <sub>STG</sub>	-55 to +150		°C	
PARAMETER	TEST CONDITIONS		SYMBOL	Max.		UNIT
Forward Voltage (1)	IF=2.0A	Tj=25°C Tj=125°C	V <sub>F</sub>	0.	• •	V
Leakage Current (1)	VR=60V	Tj=25°C Tj=90°C	I <sub>R</sub>	0.		mA
THERMAL CHARACTERISTIC		SYMBOL	Тур	ical	UNIT	
Typical junction capacitance (2)		CJ	14	40	pF	
Typical thermal resistance _ Junction to Case (3)		R⊕ <sub>JC</sub>	2	20		
Typical thermal resistance _ Junction to Ambient (3)		R⊖ <sub>JA</sub>	80		°C/W	
Typical thermal resistance _ Junction to Lead (3)		R⊕JL	35		°C/W	

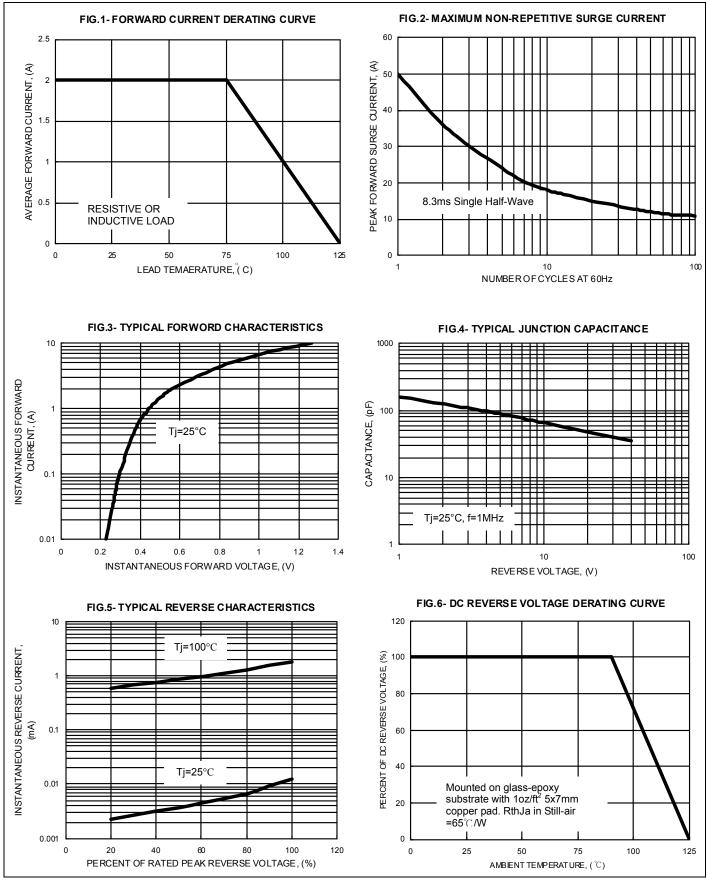
(1) 300us Pulse width, 2% Duty cycle.

Note:

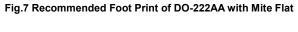
(2) Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

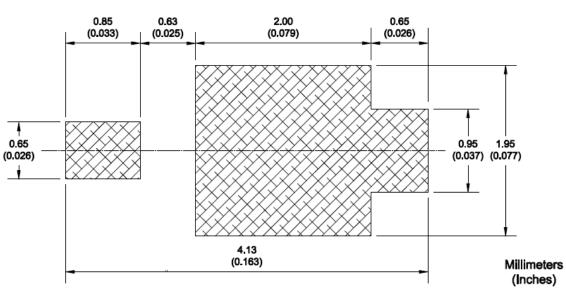
(3) Thermal Resistance test performed in accordance with JESD-51. Unit mounted on 0.75t glass-epoxy substrate with 5x7 mm copper pad. R<sub>PJL</sub> is measured at the lead of cathode band, R<sub>PJC</sub> is measured at the top centre of body.













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